



Material Content Data Sheet



Sales Product Name				BSC100N10NSF G		Issued		20. July 2018	
MA#				MA001638190					
Package				PG-TDSON-8-39		Weight*		114.85 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.418	4.72	4.72	47170	47170	
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127		
	non noble metal	iron	7439-89-6	0.049	0.04		424		
	non noble metal	copper	7440-50-8	48.649	42.37	42.42	423580	424131	
	non noble metal	copper	7440-50-8	0.025	0.02	0.02	216	216	
wire	non noble metal	copper	7440-50-8	0.025	0.02	0.02	216	216	
encapsulation	organic material	carbon black	1333-86-4	0.076	0.07		660		
	plastics	epoxy resin	-	5.986	5.21		52120		
	inorganic material	silicondioxide	60676-86-0	31.825	27.71	32.99	277093	329873	
leadfinish	non noble metal	tin	7440-31-5	1.520	1.32	1.32	13235	13235	
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1380	1380	
solder	non noble metal	tin	7440-31-5	0.081	0.07		705		
	noble metal	silver	7440-22-4	0.101	0.09		882		
	non noble metal	lead	7439-92-1	3.868	3.37	3.53	33678	35265	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		44		
	non noble metal	iron	7439-89-6	0.017	0.01		147		
	noble metal	silver	7440-22-4	0.150	0.13		1306		
	non noble metal	copper	7440-50-8	16.910	14.72	14.86	147233	148730	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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